ExpressPort[™] SFP+ 1xN

Amphenol's ExpressPort[™] SFP+ 1xN connector, when combined with the ExpressPort[™] SFP+ cage, provides data transfer speeds of up to 25 Gbps. The design of the ExpressPort[™] SFP+ connector minimizes impedance discontinuities and reflections at high data rates, and provides a 10 to 20 dB improvement in Near-End Crosstalk.

Amphenol's unique ExpressPort[™] SFP+ cage construction features EMI shielding available in the form of metal spring fingers or elastomeric gaskets. These cages also eliminate ventilation holes near the front of the cage to prevent potential catch points for the mating module EMI springs. Additional features available include lightpipes (which can be purchased with cages or separately), heat sinks, and other custom features.

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U77-A441M-2081

Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 20-position SFP+ connectors complying with SFF-8081 and SFF-8083. Ganged cages comply with industry standard SFF-8433.

General Characteristics

- RoHS Compliant
- Industry Standard Footprint
- Industry Standard EIA-364

Mechanical Characteristics

- Accepts Multiple Transceivers per SFF-8431
- Compliant Press-Fit Pins or Solder Tails (for 1x1 Cages)
- Durability: 250 Mating Cycles min

Electrical Characteristics

- Hot Swappable
- Operating Voltage: 3.3 V
- Operating Current: 0.5 A
- Differential Impedance: $100 \Omega + 10 \Omega$
- DWV: 300 V AC
- Insulation Resistance: 1000 MΩ min
- Contact Resistance: 70 mΩ max

Packaging

- Tape and Reel Packaging: Connector or 1x1 Cage
- Tray Packaging: Cage of all Sizes
- Bulk Packaging: Dust Cover

Materials

- Cage
 - o Base Material: Copper Alloy
 - o Plating: Nickel or Tin
 - o Light Pipe: Optical Grade Polycarbonate
 - o Heat Sink: Aluminum Alloy
 - o Heat Sink Clip: Stainless Steel
 - o Dust Cover: Thermoplastic
- Connector
 - o Contact Base Material: Copper Alloy
 - o Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
 - o Housings: Glass Reinforced, Lead-Free Solder Reflow Process Compatible Thermoplastic, UL94V-0 Rated

1x2

Temperature Rating

- Operating Temperature: -55°C to +85°C
- Storage Temperature: -55°C to +105°C

Configurations (Rows x Ports per Row)

- 1x1
- 1x3 1x4
- 1x6

Options

- Dust Cover
- Round Light Pipe
- Heat Sink
- EMI Shielding
- o Metal Spring Fingers
- o Conductive Elastomeric Gasket



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Ordering Information





Website: www.amphenol-highspeed.com All specifications are subject to change without notice. Email: cages@amphenol-highspeed.com